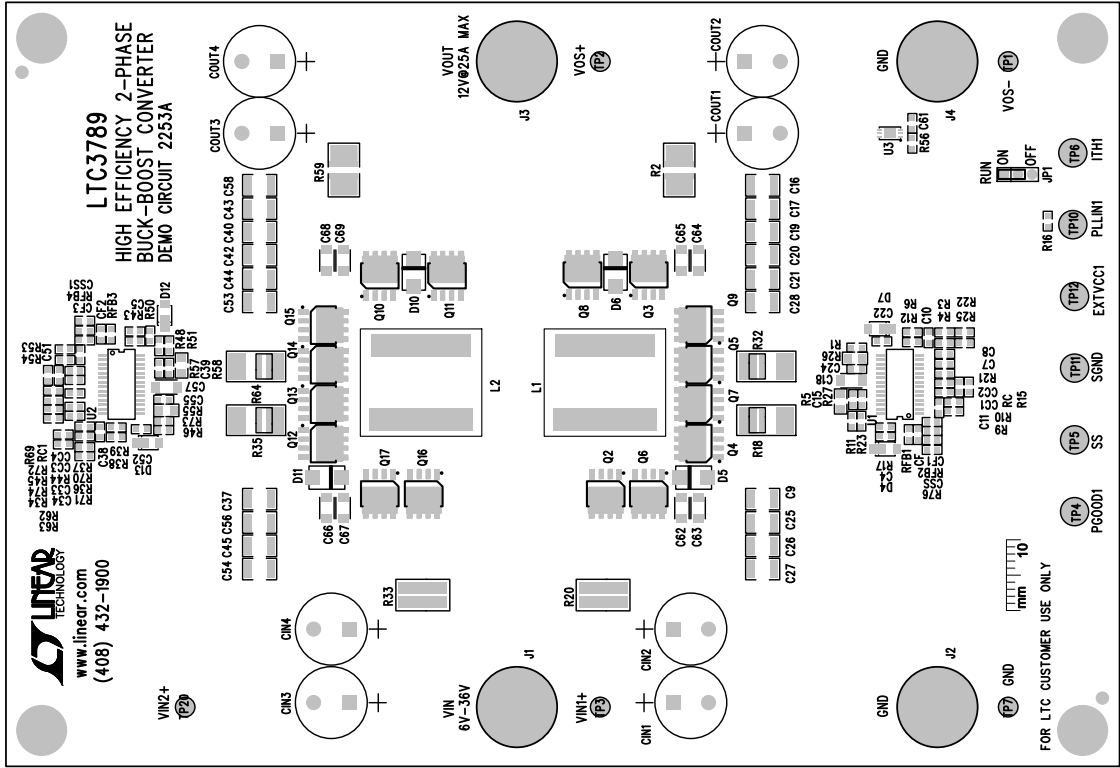
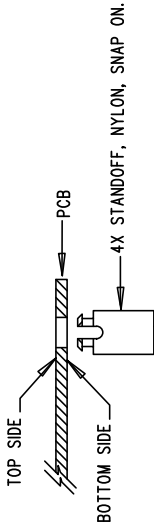


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	1	PRODUCTION	Jeffrey W. 15/6/2014



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANLIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		LTC3789 HIGH EFFICIENCY 2-PHASE BUCK-BOOST CONVERTER	
PCB DES.	HZ	SIZE	IC NO. LTC3789EGN
APP ENG.	Jeffrey W.	REV.	1
		N/A	DEMO CIRCUIT 2253A
SCALE = NONE		FILENAME: DC2253A.PCB	SHT 1 OF 1